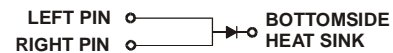
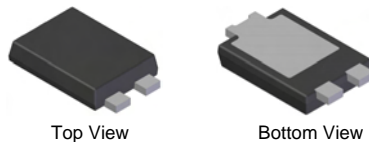


## Features

- Designed as Bypass Diodes for Solar Panels
- Selectively Rated for 200°C Maximum Junction Temperature for High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Forward Voltage Drop
- Excellent High Temperature Stability
- **Lead Free Finish, RoHS Compliant (Note 1)**

## Mechanical Data

- Case: PowerDI<sup>®5</sup>
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.093 grams (approximate)



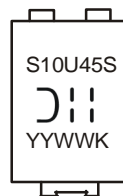
**Note:** Pins Left & Right must be electrically connected at the printed circuit board.

## Ordering Information (Note 2)

Part Number	Case	Packaging
SBR10U45SP5-13	PowerDI <sup>®5</sup>	5000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see *EU Directive 2002/95/EC Annex Notes*  
2. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



S10U45S = Product Type Marking Code  
D||| = Manufacturers' Code Marking  
K = Factory Designator  
YYWW = Date Code Marking  
YY = Last Two Digits of Year (ex: 08 for 2008)  
WW = Week code (01 - 53)

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	45	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>RM</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	32	V
Average Rectified Output Current	I <sub>O</sub>	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	275	A
Repetitive Peak Avalanche Power (1μs, 25°C)	P <sub>ARM</sub>	30000	W

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	R <sub>θJA</sub>	73	°C/W
Thermal Resistance Junction to Ambient (Note 3)			
Thermal Resistance Junction to Ambient (Note 4)			
Operating Temperature Range	T <sub>J</sub>	-65 to +150	°C
		V <sub>R</sub> ≤ 80% V <sub>RRM</sub>	
		V <sub>R</sub> ≤ 50% V <sub>RRM</sub>	
Storage Temperature Range	T <sub>STG</sub>	≤200	°C
		-65 to +175	

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V <sub>(BR)R</sub>	45	-	-	V	I <sub>R</sub> = 0.3mA
Forward Voltage Drop	V <sub>F</sub>	-	-	0.42	V	I <sub>F</sub> = 8A, T <sub>J</sub> = 25°C
		-	0.42	0.47		I <sub>F</sub> = 10A, T <sub>J</sub> = 25°C
		-	0.38	0.41		I <sub>F</sub> = 10A, T <sub>J</sub> = 125°C
Leakage Current (Note 5)	I <sub>R</sub>	-	0.05	0.3	mA	V <sub>R</sub> = 45V, T <sub>J</sub> = 25°C
		-	-	15		V <sub>R</sub> = 45V, T <sub>J</sub> = 100°C
		-	28.0	75		V <sub>R</sub> = 45V, T <sub>J</sub> = 150°C

- Notes:
- FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
  - Polymide PCB, 2oz. Copper. Cathode pad dimensions 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 14.4mm.
  - Short duration pulse test used to minimize self-heating effect.

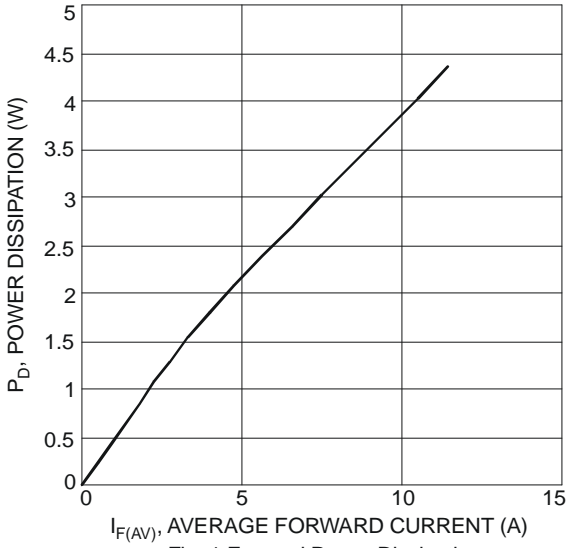


Fig. 1 Forward Power Dissipation

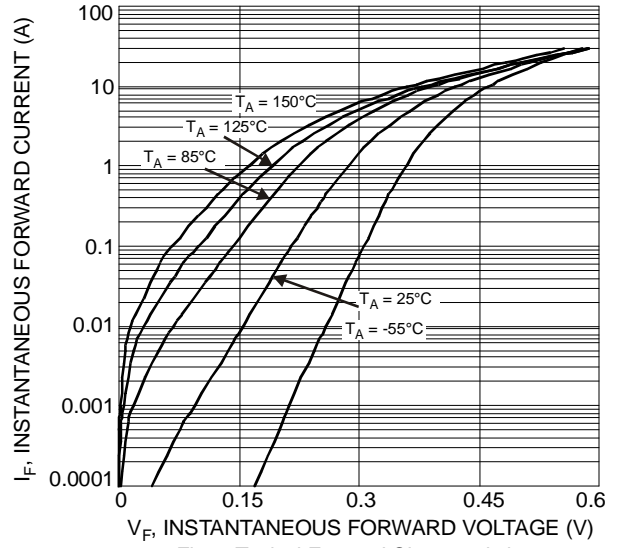


Fig. 2 Typical Forward Characteristics

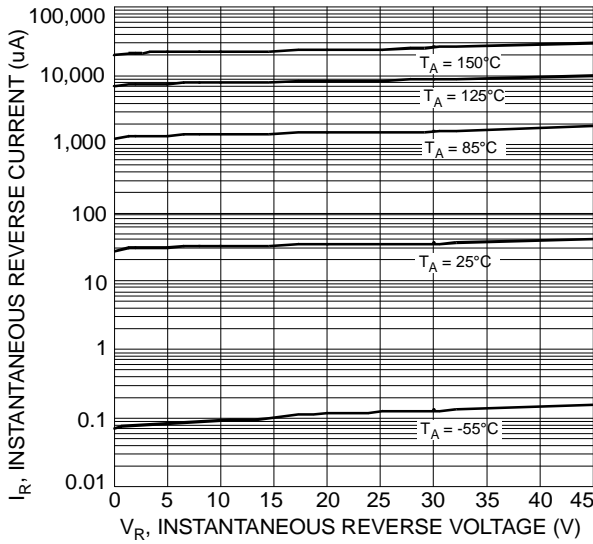


Fig. 3 Typical Reverse Characteristics

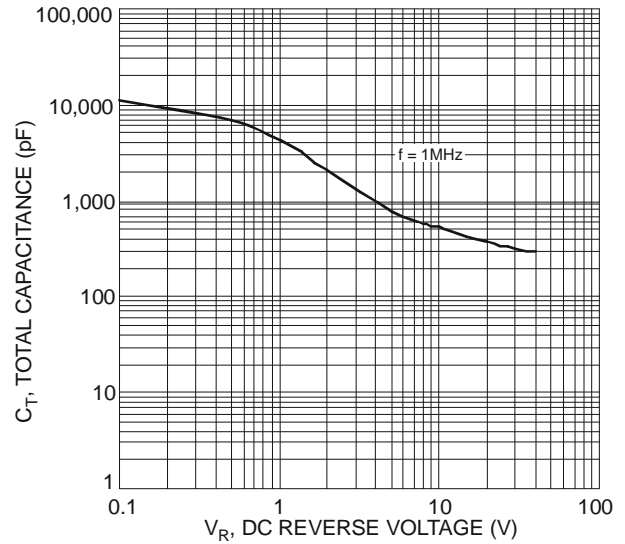


Fig. 4 Total Capacitance vs. Reverse Voltage

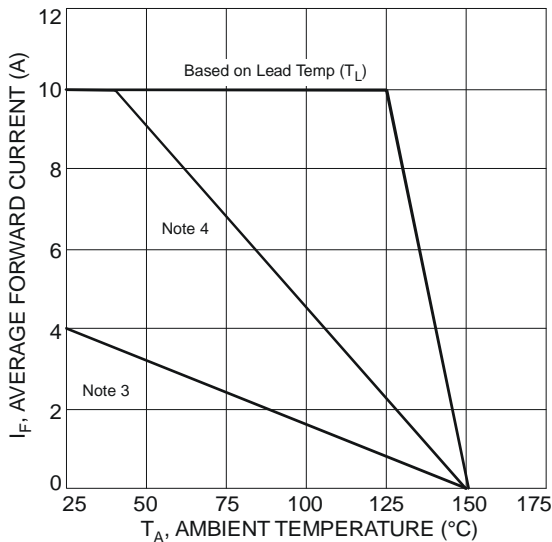


Fig. 5 Forward Current Derating Curve

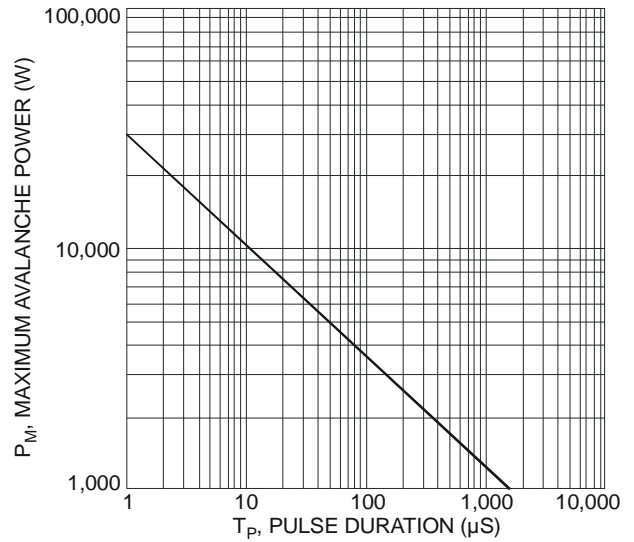
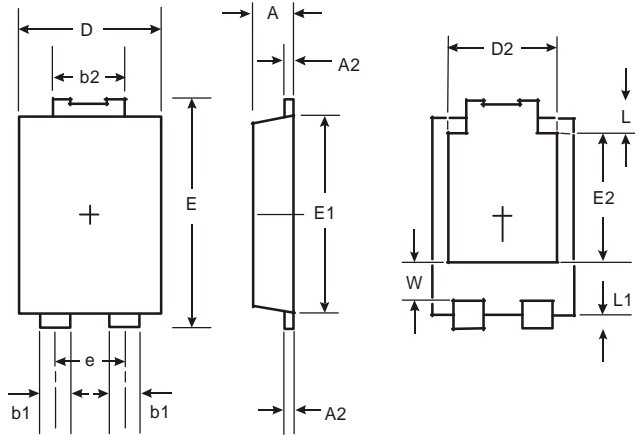


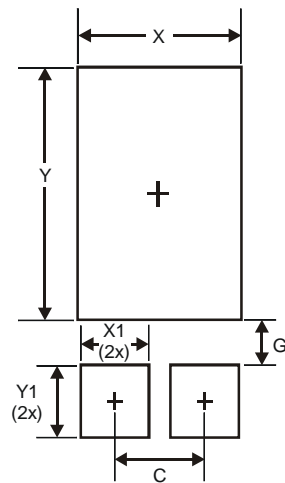
Fig. 6 Maximum Avalanche Power

**Package Outline Dimensions**



PowerDI <sup>®</sup> 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
<b>All Dimensions in mm</b>		

**Suggested Pad Layout**



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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